## ABSTRACT OF THE DISCLOSURE

The invention ensures satisfactory connections upon establishment of electrical connections between pad electrodes provided on a to-be-transferred piece and pad electrodes provided on a transfer destination substrate. A transfer chip according to the present invention is formed on a first substrate and transferred from the first substrate to a second substrate having wiring. The transfer chip serves as a transfer unit including at least a thin-film electrical circuit formed of stacked films and a plurality of pad electrodes to establish connections between the thin-film electrical circuit and another circuit. The pad electrodes are arranged over the entire one surface of the transfer chip and cover thin-film elements or thin-film wiring included in the thin-film electrical circuit provided below the pad electrodes. Accordingly, the tops of rough surface portions of the pad electrodes have approximately the same height.